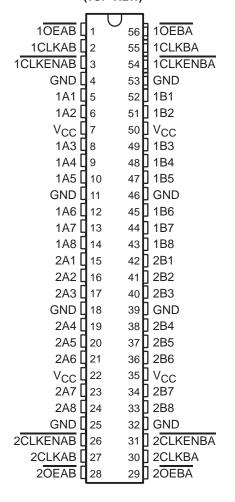
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- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V **Operation and Low-Static Power** Dissipation
- **Members of the Texas Instruments** *Widebus*™ Family
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V<sub>CC</sub>)
- **Support Unregulated Battery Operation** Down to 2.7 V
- Typical V<sub>OLP</sub> (Output Ground Bounce) < 0.8 V at  $V_{CC}$  = 3.3 V,  $T_A$  = 25°C
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V **Using Machine Model** (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- **Bus-Hold Data Inputs Eliminate the Need** for External Pullup Resistors
- **Support Live Insertion**
- Distributed V<sub>CC</sub> and GND Pin Configuration **Minimizes High-Speed Switching Noise**
- Flow-Through Architecture Optimizes **PCB Layout**
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package **Using 25-mil Center-to-Center Spacings**

#### SN54LVT16952 . . . WD PACKAGE SN74LVT16952...DGG OR DL PACKAGE (TOP VIEW)



## description

The 'LVT16952 are 16-bit registered transceivers designed for low-voltage (3.3-V)  $m V_{CC}$  operation, but with the capability to provide a TTL interface to a 5-V system environment. These devices can be used as two 8-bit transceivers or one 16-bit transceiver. Data on the A or B bus is stored in the registers on the low-to-high transition of the clock (CLKAB or CLKBA) input provided that the clock-enable (CLKENAB or CLKENBA) input is low. Taking the output-enable (OEAB or OEBA) input low accesses the data on either port.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74LVT16952 is available in TI's shrink small-outline (DL) and thin shrink small-outline (DGG) packages, which provide twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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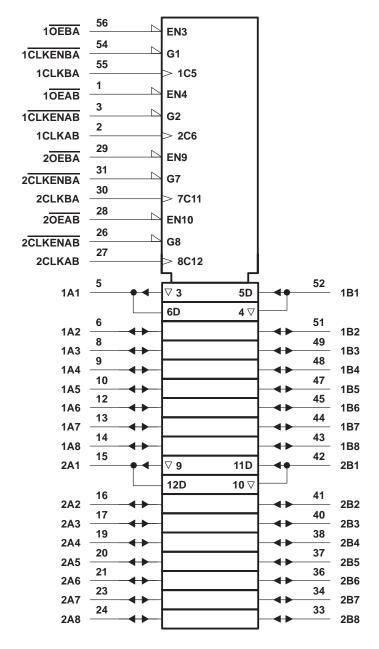


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## description (continued)

The SN54LVT16952 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74LVT16952 is characterized for operation from –40°C to 85°C.

## logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

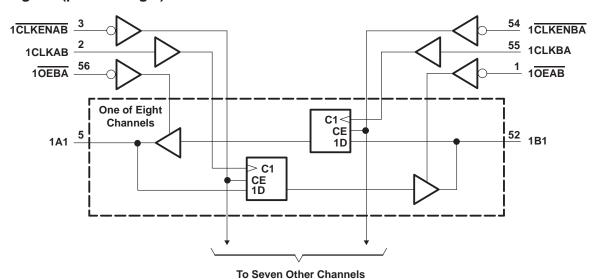


#### **FUNCTION TABLE**†

	INPUT	S		OUTPUT
CLKENAB	CLKAB	OEAB	Α	В
Н	Χ	L	Χ	в <sub>0</sub> ‡
Х	L	L	Χ	B <sub>0</sub> ‡
L	$\uparrow$	L	L	L
L	$\uparrow$	L	Н	Н
Х	X	Н	Χ	Z

<sup>†</sup> A-to-B data flow is shown; B-to-A data flow is similar but uses CLKENBA, CLKBA, and OEBA.

## logic diagram (positive logic)



2CLKENAB
2CLKBA
2OEBA
2OEBA
2OTEBA
2O



To Seven Other Channels

<sup>‡</sup>Level of B before the indicated steady-state input conditions were established

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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	–0.5 V to 4.6 V
Input voltage range, V <sub>I</sub> (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, V <sub>O</sub> (see Note 1) .	–0.5 V to 7 V
Current into any output in the low state, IO: SN54LVT16952	96 mA
SN74LVT16952	128 mA
Current into any output in the high state, I <sub>O</sub> (see Note 2): SN54LVT16952	48 mA
SN74LVT16952	64 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–50 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	
Maximum power dissipation at T <sub>A</sub> = 55°C (in still air) (see Note 3): DGG package	1 W
DL package	1.4 W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
  - 2. This current flows only when the output is in the high state and  $V_O > V_{CC}$ .
  - 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the *ABT Advanced BiCMOS Technology Data Book*.

#### recommended operating conditions (see Note 4)

			SN54LV	T16952	SN74LV	T16952	UNIT
			MIN	MAX	MIN	MAX	UNII
VCC	Supply voltage		2.7	3.6	2.7	3.6	V
VIH	High-level input voltage		2		2		V
VIL	Low-level input voltage			0.8		0.8	V
VI	Input voltage			5.5		5.5	V
ІОН	High-level output current			-24		-32	mA
loL	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.



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## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DARAMETER	_	FOT CONDITIONS		SN5	4LVT16	952	SN7	'4LVT16	952	
PARAMETER	'	EST CONDITIONS		MIN	TYP <sup>†</sup>	MAX	MIN	TYP <sup>†</sup>	MAX	UNIT
VIK	$V_{CC} = 2.7 \text{ V},$	I <sub>I</sub> = -18 mA				-1.2			-1.2	V
	$V_{CC} = MIN \text{ to } MAX^{\ddagger},$	$I_{OH} = -100 \mu A$		V <sub>CC</sub> -0.	2		V <sub>CC</sub> -0.	.2		
\/a	$V_{CC} = 2.7 \text{ V},$	$I_{OH} = -8 \text{ mA}$		2.4			2.4			V
VOH	VCC = 3 V	I <sub>OH</sub> = -24 mA		2						V
	VCC = 3 V	I <sub>OH</sub> = -32 mA					2			
	V <sub>CC</sub> = 2.7 V	I <sub>OL</sub> = 100 μA				0.2			0.2	
	VCC = 2.7 V	I <sub>OL</sub> = 24 mA				0.5			0.5	
V <sub>OL</sub>		I <sub>OL</sub> = 16 mA				0.4			0.4	V
VOL	V <sub>CC</sub> = 3 V	I <sub>OL</sub> = 32 mA				0.5			0.5	V
	ACC = 2 A	I <sub>OL</sub> = 48 mA				0.55				
		I <sub>OL</sub> = 64 mA							0.55	
	$V_{CC} = 3.6 \text{ V},$	$V_I = V_{CC}$ or GND	Control			±1			±1	
	$V_{CC} = 0$ or MAX $^{\ddagger}$ ,	V <sub>I</sub> = 5.5 V	inputs			10			10	
l <sub>l</sub>		V <sub>I</sub> = 5.5 V				100			20	μΑ
	V <sub>CC</sub> = 3.6 V	VI = VCC	A or B ports§	1		1		1		
		V <sub>I</sub> = 0				-5			<del>-</del> 5	
l <sub>off</sub>	$V_{CC} = 0$ ,	$V_I$ or $V_O = 0$ to 4.5 $V$							±100	μΑ
ha is	V <sub>CC</sub> = 3 V	V <sub>I</sub> = 0.8 V	A or B ports	75			75			μА
l(hold)	∧CC = 2 ∧	V <sub>I</sub> = 2 V	A of B ports	-75			-75			μΑ
IOZH	$V_{CC} = 3.6 \text{ V},$	V <sub>O</sub> = 3 V				1			1	μΑ
lozL	$V_{CC} = 3.6 \text{ V},$	V <sub>O</sub> = 0.5 V				-1			-1	μΑ
			Outputs high			0.12			0.12	
Icc	$V_{CC} = 3.6 \text{ V},$	$I_{O} = 0$ ,	Outputs low		5		5		mA	
icc	V <sub>I</sub> = V <sub>CC</sub> or GND	Outputs disabled				0.12			0.12	1117 (
ΔI <sub>CC</sub> ¶		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$ , One input at $V_{CC} - 0.6 \text{ V}$ , Other inputs at $V_{CC}$ or GND				0.2			0.2	mA
C <sub>i</sub>	V <sub>I</sub> = 3 V or 0				4			4		pF
C <sub>io</sub>	$V_O = 3 V \text{ or } 0$				13			13		pF

<sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ . ‡ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

<sup>§</sup> Unused pins at V<sub>CC</sub> or GND

This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

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# timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

				SN54LV	T16952			SN74LV	T16952			
			V <sub>CC</sub> =		V <sub>CC</sub> =	V <sub>CC</sub> = 2.7 V		3.3 V 3 V	V <sub>CC</sub> = 2.7 V		UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
fclock	Clock frequency		0	150	0	150	0	150	0	150	MHz	
	tw Pulse duration	CLKEN high	3.3		3.3		3.3		3.3		ns	
t <sub>W</sub>	ruise duration	CLK high or low	3.3		3.3		3.3		3.3		115	
	Catum times	A or B before CLK	2.6		3.3		2.1		2.9			
t <sub>su</sub>	Setup time	CLKEN before CLK	1.2		1.6		1.2		1.6		ns	
t.	Hold time	A or B after CLK	0.7		0.7		0.7		0.7			
<sup>t</sup> h	rioid time	CLKEN after CLK	1.4		1.5		1.4		1.5		ns	

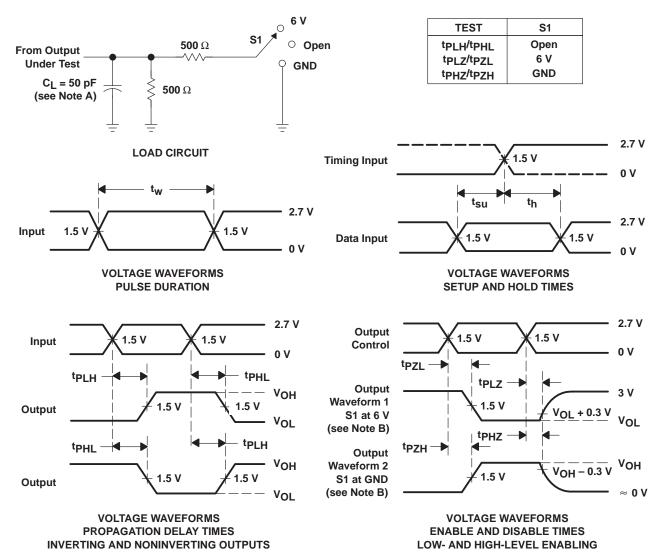
# switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

		TO (OUTPUT)		SN54LV	T16952		SN74LVT16952					
PARAMETER	FROM (INPUT)			V <sub>CC</sub> = 3.3 V ± 0.3 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V			V <sub>CC</sub> = 2.7 V	
			MIN	MAX	MIN	MAX	MIN	TYP	MAX	MIN	MAX	
f <sub>max</sub>			150		150		150			150		MHz
t <sub>PLH</sub>	CLKBA or	A or B	1.6	5.7		7.4	2	3.4	5.8		7.1	ns
t <sub>PHL</sub>	CLKAB	AUIB	2	6		7	2	3.4	5.8		6.9	115
<sup>t</sup> PZH	OEBA or	A or B	1	5		7.3	1	2.7	5.6		6.7	ns
<sup>t</sup> PZL	OEAB	AOIB	1.2	5.2		5.9	1.2	2.7	6.5		8	115
<sup>t</sup> PHZ	OEBA or	A or B	1.8	6.7		7.3	2.3	3.9	6.3		6.9	ns
tPLZ	OEAB	AUID	1.2	5.8		6	2.2	3.9	5.1		5.3	115

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .



#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq 2.5 \text{ ns.}$
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
SN74LVT16952DGGR	Active	Production	TSSOP (DGG)   56	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT16952
SN74LVT16952DGGR.B	Active	Production	TSSOP (DGG)   56	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT16952
SN74LVT16952DGGRG4	Active	Production	TSSOP (DGG)   56	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT16952
SN74LVT16952DGGRG4.B	Active	Production	TSSOP (DGG)   56	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT16952
SN74LVT16952DL	Active	Production	SSOP (DL)   56	20   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT16952
SN74LVT16952DL.B	Active	Production	SSOP (DL)   56	20   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT16952

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



## **PACKAGE OPTION ADDENDUM**

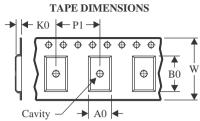
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## **PACKAGE MATERIALS INFORMATION**

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## TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVT16952DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.9	14.7	1.4	12.0	24.0	Q1
SN74LVT16952DGGRG4	TSSOP	DGG	56	2000	330.0	24.4	8.9	14.7	1.4	12.0	24.0	Q1

## **PACKAGE MATERIALS INFORMATION**

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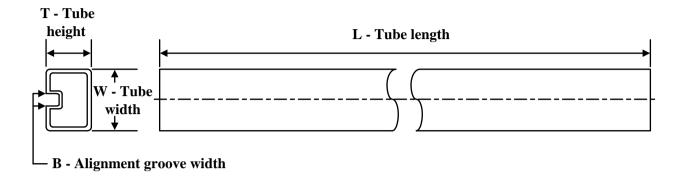
#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVT16952DGGR	TSSOP	DGG	56	2000	356.0	356.0	45.0
SN74LVT16952DGGRG4	TSSOP	DGG	56	2000	356.0	356.0	45.0

## **PACKAGE MATERIALS INFORMATION**

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## **TUBE**

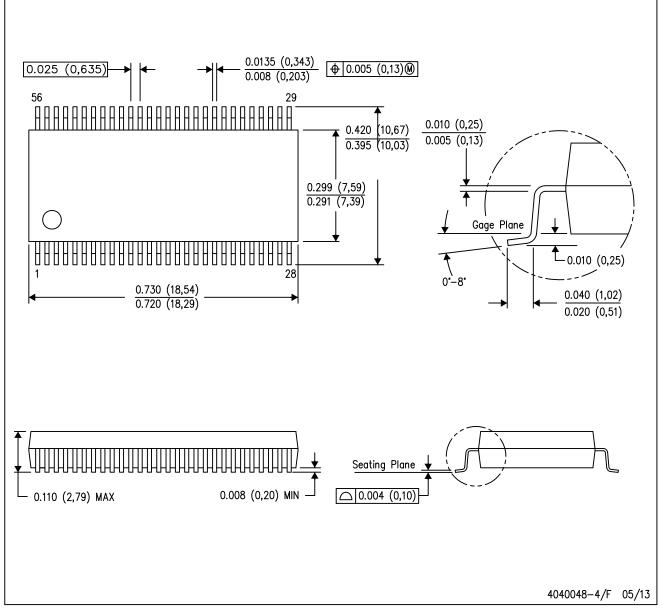


#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74LVT16952DL	DL	SSOP	56	20	473.7	14.24	5110	7.87
SN74LVT16952DL.B	DL	SSOP	56	20	473.7	14.24	5110	7.87

## DL (R-PDSO-G56)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

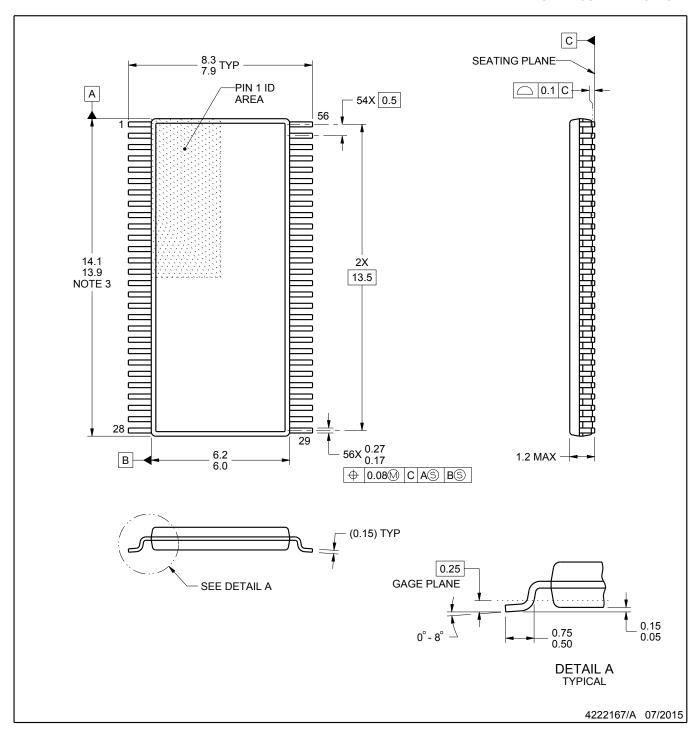
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.





SMALL OUTLINE PACKAGE



#### NOTES:

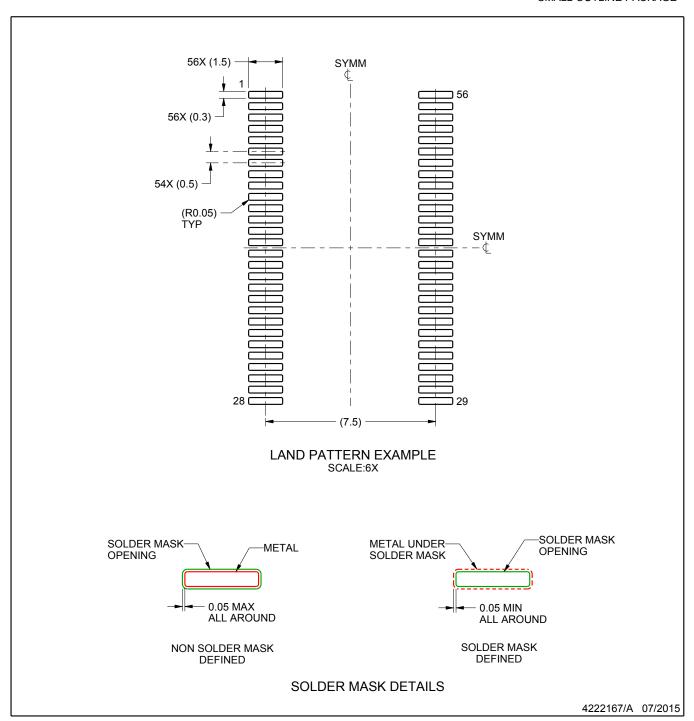
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
  4. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE

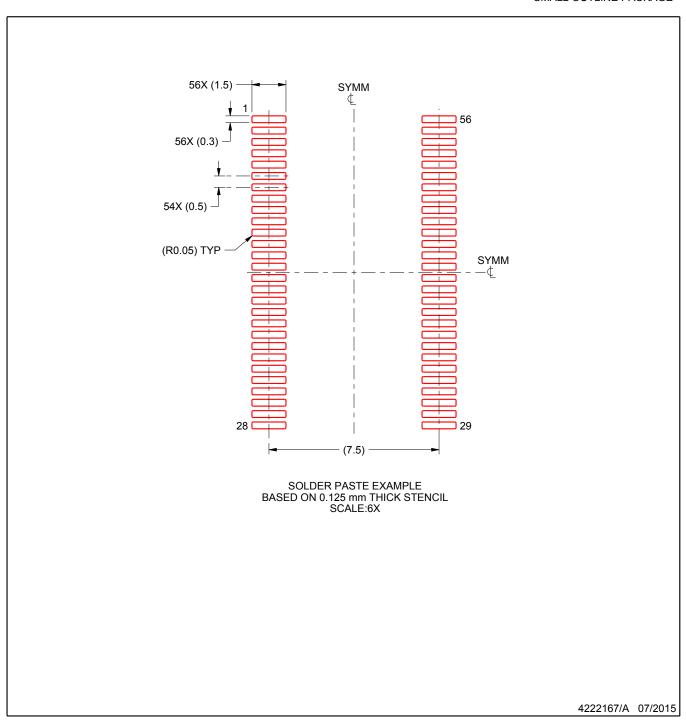


NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



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